Supplier Name:	Texas Instruments Inc. (DUNS# 00-732-1904)
Contact Info:	<u>ti.com/support</u>
Form/Declaration Type:	Distribute - RoHS and IEC 62474 DB
Created on:	06/12/2022

#### Details for "TPS7A2033PYCJR"

#### **Current Product Information**

TI part number	Lead finish/Ball material	MSL rating/peak reflow	Assembly site	Package   Pins	Package body size (mm)	Total device mass (mg)*
TPS7A2033PYCJR	SNAGCU	Level-1-260C-UNLIM	TI Semiconductor	YCJ   4	.616x.616x.178	0.2

#### \*Total Device Mass

The summary mass is a rounded value and will be within approximately +/- 10% of the detailed mass value.

# **Environmental Ratings Information**

RoHS	REACH	Green	IEC 62474 DB	
Yes	Yes	Yes	Yes	

## **Component Information**

			Homogeneous Material Level		Component Level			
Component	Substance	CAS Number	Amount (mg)	Percentage %	ppm	Percentage %	ppm	
Semiconductor Device	Semiconductor Device							
Ceramics / Glass	Doped Silicon	7440-21-3	0.157308	100	1000000	74.933906	749339	
Sub-Total			0.157308	100	1000000	74.933906	749339	
Solder Bump								
Copper and Its Alloys	Copper	7440-50-8	0.000316	0.600521	6005	0.150527	1505	
Other Nonferrous Metals and Alloys	Tin	7440-31-5	0.050253	95.499895	954999	23.938093	239381	
Precious Metals	Silver	7440-22-4	0.002052	3.899584	38996	0.977473	9775	
Sub-Total			0.052621	100	1000000	25.066094	250661	
Total			0.209929			100	1000000	

#### Important Note

The ppm calculations are at the **homogeneous material** level and are maximum concentration values. The ppm displayed represents the **homogeneous material** with the highest ppm

for that substance. The amount (mg) calculations represent the maximum total amount of each substance within the component.

The ppm calculations are at the **component** level and are average concentration values. The amount (mg) calculations represent the average total amount of each substance within the **component**. See Glossary of Terms for more details.

## Important Part Information

There is a remote possibility the Customer Part Number (CPN) your company uses could reference more than one TI part number. This is due to two or more users (EMSIs or subcontractors) using the same CPN for different TI part numbers. If this occurs, please check your Customer Part Number and cross reference it with the TI part number seen on this page.

## **Product Content Methodology**

For an explanation of the methods used to determine material weights, See Product Content Methodology

## Material Declaration Certificate for Semiconductor IC Packaged Products

TI certifies that the material content information provided by TI is representative and accurate to the best of their knowledge based on material information provided by its suppliers and their combination into finished IC packaged products. TI semiconductor products designated to be "Pb-free", "Green" or "RoHS Exempt" fully meets the latest EU RoHS Directive requirements along with other legislation as seen in the former JIG-101 list that has been transferred to the IEC 62474 database.

## Important Information/Disclaimer

TI bases its material content information on information provided by third-party suppliers and has taken, and continues to take, reasonably diligent steps to provide any required or available information. TI may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers may consider certain information to be proprietary, and thus certain information may not be available for release by TI. The material content information is

# provided by TI "as is." For additional information, please contact TI customer support.

# Signature: (click here for a fuller statement with a signed certificate)

Name/Title: Hubie Payne, Vice President, Worldwide SC Quality For further environmental statements, please go to www.ti.com/ecoinfo Created on: 06/12/2022

RoHS: Means TI semiconductor products that are compliant with the current RoHS requirement that the maximum concentration values of the ten substances listed in RoHS Annex II do not exceed 0.1 % by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI semiconductor products labeled as "RoHS Compliant" are suitable for use in specified lead-free processes. TI may also reference these types of semiconductor products as "Pb-Free." These TI semiconductor products are also fully compliant with GADSL and the IEC 62474 database for electronic requirements.

RoHS Exempt: Means TI semiconductor products that contain lead (Pb) above the RoHS Annex II threshold, but that fall within one of the specific RoHS exemptions noted above or documented in http://www.ti.com/lit/pdf/szzq088

Green: Means the content of Chlorine (Cl) and Bromine (Br)-based flame retardants meet JS709B low halogen requirements of <=1 000ppm threshold; Antimony trioxide (Sb203) contained in halogen based flame retardant materials meets the <=1 000ppm threshold requirement; and Beryllium Oxide (BeO) is <=1000ppm.